Overview

HP ZBook Studio G7 Mobile Workstation



Top View (Premium keyboard layout)

- 1. Clickpad
- 2. Fingerprint sensor (optional)
- 3. HP Premium backlit Keyboard
- 4. Layout: ctrl, fn, Windows, alt, space bar, alt, menu, ctrl layout
- 5. Power button (or power on by opening the lid)

- 6. Speakers
- 7. Camera
- 8. IR Camera
- 9. Microphones



Overview



Top View (Z Command keyboard layout; US Only)

- 1. Clickpad
- 2. Fingerprint sensor (optional)
- 3. HP Z Command backlit Keyboard
- 4. Layout: fn, Windows, alt, ctrl, space bar, ctrl, alt, menu, layout
- 5. Power button (or power on by opening the lid)

- 6. Speakers
- 7. Camera
- 8. IR Camera
- 9. Microphones

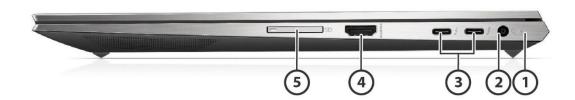


Overview



Left

- 1. Nano security lock slot
- 2. (1) USB 3.1 Gen 1 Type A charging port
- Leit
 - 3. Side Vent
 - 4. Headphone/microphone combo jack



Right (configurations without NVIDIA RTX Graphics)

- 1. Battery Charging LED
- 2. 4.5mm AC Power connector
- 3. (2) USB Type-C[®] with Thunderbolt™

- 4. HDMI 2.0 with Discrete Graphics / HDMI 1.4 with UMA graphics (HDMI cable is not included)
- 5. SD Card Reader (SD Media not included)



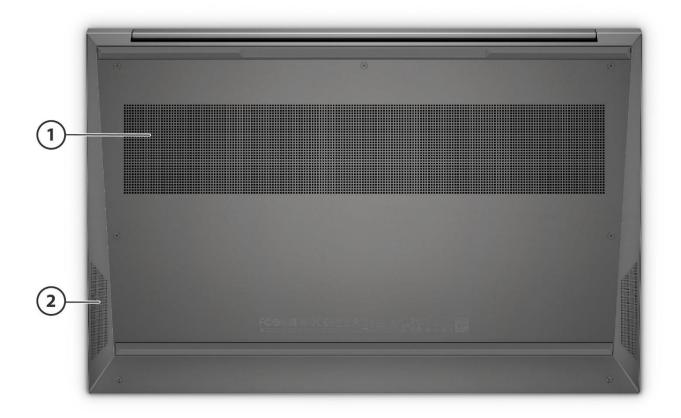
Overview



Right (configurations with NVIDIA RTX Graphics)

- 1. Battery Charging LED
- 2. 4.5mm AC Power connector
- 3. (2) USB Type-C[®] with Thunderbolt™

- 4. mini DisplayPort™ 1.4 (mini DisplayPort cable is not included)
- 5. SD 4.0 Card Reader (SD Media not included)



Bottom (configurations without NVIDIA RTX Graphics)

1. Fan Venting

2. Speakers



Overview



Bottom (configurations with NVIDIA RTX Graphics)

1. Fan Venting

2. Speakers

Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro¹, powered by HP's collaboration and connectivity technology.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Quadro® T-Series and RTX graphics²; Certified and supported for the apps you use every day.
- Take multitasking to the next level with up to the 10th gen Intel® Core™ i9 or Intel® Xeon® processor^{3,4} designed to handle complex, multithreaded apps like Adobe Premiere Pro®, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.⁵
- Power through projects with up to 32 GB SDRAM⁶ for fast rendering, editing and simulating.
- Blitz through multiple tasks and ditch external drives with up to 2 TB local NVMe storage⁷
- Tirelessly re-engineered from the ground up, this is superior design. Vapor chamber²² cooling and liquid-crystal polymer thermals equip you to run at max performance. Our astonishingly quiet, comfortable keyboard keeps you in the zone. Check out the HP ZBOOK CREATE AND ZBOOK STUDIO INNOVATIONS WHITEPAPER on the grounds up innovations.
- 4 Speakers (2 tweeters and 2 woofers) speakers custom tuned by Bang and Olufsen surround you in a rich sound space so you hear music the way the audio engineers intended. Featuring the most powerful speakers with the greatest levels of bass on any HP notebook.
- Connect to everything you need with a wide-range of connectivity options: Dual USB-C[®] Thunderbolt[™], HDMI¹¹ (only on configurations with RTX graphics), USB 3.1 Type A charging port, headphone jack, and AC port.
- Choice of displays²:
 - 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) IPS eDP + PSR anti-glare, 100% DCI-P3, 600 nits VESA Display Next Gen HP DreamColor Panel;
 - 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 100% sRGB at 400 nits low power (1W) panel;
 - 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 72% NTSC at 1000 nits HP Sure View Reflect Integrated Privacy Panel;
 - 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) UWVA eDP + PSR Brightview 100% DCI-P3, 400 nits OLED VESA Display HDR 500 Certified panel with Corning® Gorilla® Glass 6 Touch Screen
- A completely revamped standby system means you're ready to work the moment inspiration strikes. With no sleep mode
 and no off mode, the modern standby keeps your rig connected and on demand whenever you need it.
- Transfer files over Wi-Fi® up to 3x faster with Wi-Fi 6¹²
- Have confidence with the HP's most secure mobile workstations. ¹³ Instantly protect against visual hacking with HP Sure View Reflect ¹⁴, and defend against firmware and malware attacks with HP Sure Start Gen6 ^{10,15} and HP Sure Sense. ^{9,16}
- A highly recyclable & lightweight aluminum exterior with 5x the abrasion resistance of painted carbon fiber allows for a more durable, thin, and recyclable device.²¹
- HP ZBook Studio G7 is designed to undergo extensive MIL-STD 810H testing, and has passed 21 of the MIL-STD 810H tests.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 3¹⁸ transfers and the flexibility to run up to two external 4K displays. ^{19, 20}

¹Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

²Sold separately or as an optional feature.

NVIDIA®, the NVIDIA® logo, NVIDIA Turing™ and NVIDIA® GeForce® are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries

³Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

⁴Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information. "

⁵Adobe and Autodesk software sold separately.



Overview

⁶Up to 32GB memory is an optional, configurable feature.

⁷For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB (for Windows 10) of system disk is reserved for system recovery software.

⁹ HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

¹⁰HP Sure Start Gen6 is available on select HP PCs.

¹¹miniDisplayPort cables are sold separately; HDMI Cables are sold separately

¹²Wi-Fi 6 offers up to 3x faster file transfer speeds than Wi-Fi[®] 5 Based on Wi-Fi 5 80MHz and Wi-Fi 6 160MHz minimum requirements when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported

¹³Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.

¹⁴HP Sure View integrated privacy screen is an optional feature that must be configured at purchase.

¹⁶ HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

¹⁷Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

¹⁸HP Thunderbolt Dock with Thunderbolt™ 3 sold separately.

¹⁹External displays sold separately.

²⁰Optional hybrid graphics is required to run up to two external 4K displays.

²¹HP Internal Testing conducted on July 2018, using ASTM International Standards Worldwide using test method ASTM D4060

²² The HP Z VaporForce (vapor chamber) is only available on configurations with NVIDIA® Quadro® RTX Graphics.

NOTE: See important legal disclosures for all listed specs in their respective feature's sections.



Features

OPERATING SYSTEM

Preinstalled OS Windows 10 Pro 64 - HP recommends Windows 10 Pro for business.¹

Windows 10 Home 641

Windows 10 Pro for Workstations 641

Ubuntu 20.04² FreeDOS 3.0

Supported OS⁴ Windows 10 64 Enterprise

Supported Version HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of

Windows 10, please see: https://support.hp.com/document/c05195282.

PROCESSOR

Intel® Xeon® W 10885M with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB L3 cache, 8 cores) supporting Intel® vPro® technology 1.2,3,4,5

10th Generation Intel® Core™ i9 10885H with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB L3 cache, 8 cores) supporting Intel® vPro® technology ^{1,2,3,4,5}

10th Generation Intel® Core™ i7 10850H with Intel® UHD Graphics (2.7 GHz base frequency, up to 5.1 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores) supporting Intel® vPro® technology ^{1,2,3,4,5}

10th Generation Intel® Core™ i7 10750H with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)^{1,2,3,4}

10th Generation Intel® Core™ i5 10400H with Intel® UHD Graphics (2.6 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) supporting Intel® vPro® technology ^{1,2,3,4,5}

⁵ For full Intel® vPro® functionality, Windows, a vPro supported processor, vPro enabled Q370 chipset or higher and vPro enabled WLAN card are required. Some functionality, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.



¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³ Ubuntu 20.04 to be available in the 2nd half of 2020

⁴Support to be tested and documented or web support only.

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

HP ZBook Studio G7 Mobile Workstation

QuickSpecs

Features



Features

CHIPSET

Intel® WM490 Chipset

INTEL® CORE™ 15 WITH VPRO/CORE 17 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro®, Core™ i7 with vPro®, Core™ i9 with vPro® and Xeon® with vPro® technology is a selectable feature that is available on units configured with select processors, a qualified Intel® select WLAN module and a preinstalled Windows 10 Pro 64 and above. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT)³ offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state.

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² Some functionality of Intel® Core™ i5 with vPro®/Core™ i7 with vPro®/Core™ i9 with vPro®/Xeon® with vPro® technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro®/Core i7 with vPro®/XEON® with vPro® technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

²Intel® Active Management Technology (iAMT) built-in manageability only available with Intel vPro processor + Intel vPro WLAN module

GRAPHICS

Integrated

Intel® UHD Graphics 1,2,3,4,5,6

Supports up to 3 displays including the integrated display.

Supports: HD decode, DX12, Intel® Quick Sync Video.

Max resolution for external displays: HDMI 1.4 4096x2304 @30Hz; DisplayPort via USB-C® Thunderbolt™ 4096x2304 @60Hz

Discrete

NVIDIA® Quadro® T1000 supporting Max-Q Design (4 GB GDDR6 dedicated)^{2,4,6}

NVIDIA® Quadro® T2000 supporting Max-Q Design (4 GB GDDR6 dedicated) ^{2,4,6}

NVIDIA® Quadro® RTX 3000 supporting Max-Q Design (6 GB GDDR6 dedicated) ^{2,6,8}

NVIDIA® Quadro® RTX 4000 supporting Max-Q Design (8 GB GDDR6 dedicated) ^{2,6,8}

NVIDIA® Quadro® RTX 5000 supporting Max-Q Design (16 GB GDDR6 dedicated) 2,6,8

Supports up to 4 displays through discrete graphics and dock

Supports: NVIDIA Surround Technology for NVIDIA GeForce Graphics

Max resolution for external displays: HDMI 1.4 4096x2304 @30Hz; DisplayPort via USB-C® Thunderbolt™ 4096x2304 @60Hz

 $^{^{}m 3}$ Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz



¹ UHD content required to view UHD images.

² Both UMA & Discrete configurations support 4 independent displays when on the HP Thunderbolt Dock G2 (sold separately)

⁻ Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C[®]) output port using a Type C[®]-to-DP adapter).

Features

- ⁴ HDMI cable Sold Separately
- ⁵ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.
- ⁶GPU configurations may be limited to specific GPU/Memory Configurations.
- ⁸miniDP cable sold separately.

DISPLAY

Non-touch

- 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) IPS eDP + PSR anti-glare, 100% DCI-P3, 600 nits VESA Display Next Gen HP DreamColor Panel ^{2,3,5,6}
- 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 100% sRGB at 400 nits (1W) low power panel ^{2,3,5,6}
- 39.6 cm (15.6") diagonal FHD (1920 x 1080) IPS eDP + PSR anti-glare, 72% NTSC at 1000 nits HP Sure View Reflect Integrated Privacy Panel ^{2,3,5,6}

Touch

 39.6 cm (15.6") diagonal 4K UHD (3840 x 2160) UWVA eDP + PSR Brightview 100% DCI-P3, 400 nits OLED VESA DisplayHDR 500 Certified panel with Corning® Gorilla® Glass 6 Touch Screen ^{2,3,5,6}

HP Virtual Reality Headset (sold separately)

- HP Reverb
- HP Reverb G2

¹ HP Sure View Reflect is optional and must be configured at purchase.

² UHD content required to view UHD images.

³ Resolutions are dependent upon monitor capability, and resolution and color depth settings.

⁵ Display options may be limited to specific CPU / GPU Configurations.

⁶ VESA Display HDR 500 certification is pending.

⁷Virtual Reality content is required to view Virtual Reality images

Features

STORAGE AND DRIVES*

1 M.2 Storage (PCIe NVMe™ SSD) slot¹

256 GB PCIe[®] Gen3 x4 NVMe[™] M.2 2280 TLC Solid State Drive (SSD) 512 GB PCIe[®] Gen3 x4 NVMe[™] M.2 2280 TLC Solid State Drive (SSD) 1 TB PCIe[®] Gen3 x4 NVMe[™] M.2 2280 TLC Solid State Drive (SSD)

2 TB PCle® Gen3 x4 NVMe™ M.2 2280 TLC SSD

512 GB PCle® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD)

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe) PCIe® Gen3 x4 NVMe™ Solid State Drive

SATA Not supported RAID Not supported

MEMORY

Maximum Memory

32 GB DDR4 non-ECC SDRAM^{1,2} Memory soldered down. Supports Dual Channel Memory³ System Runs at: 2933



¹M.2 Storage Slot does not support SATA drives

¹Memory is soldered down and not upgradeable

²Memory configurations may be limited to specific CPU / GPU Configurations.

³Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Features

NETWORKING/COMMUNICATIONS

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro® 1,2,3 Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro® 1

¹Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

²Some functionality of vPro®, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro® technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined.

³Intel® Active Management Technology (iAMT) built-in manageability only available with Intel vPro processor + Intel vPro WLAN module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, quad speakers (2 tweeters and 2 woofers), HP World Facing Microphone and dual array digital microphones, functions keys for volume up and down, combo microphone/headphone jack, HD audio with 150Hz Bass Roll off

Camera^{1, 2}

720p HD with Temporal Noise Reduction webcam with IR

- ¹ HD content required to view HD images.
- ² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, with drain and DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

HP Premium Quiet Z Command Keyboard¹, full-size, spill-resistant, backlit, with drain and DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

Pointing Devices

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Buttons and Function Keys

Discrete buttons provide easy access to the following features:

F1 – Display Switching

F2 – HP Sure View on/off (if configured)

F3 - Brightness Down

F4 – Brightness Up

F5 - Audio mute

F6 - Volume down

F7 - Volume up

F8 – Microphone mute

F9 – Keyboard backlight

F10 - Insert

F11 – Airplane Mode on/off

F12 - Programmable Key

Print Screen

Power Button on/off

Delete

Fn key lock

Hidden Function Keys:

Fn+R=Break

Fn+S=Sys Rq

Fn+C=Scroll Lock

Fn+W=Pause

SOFTWARE AND SECURITY

Workstation ISV Certifications

See the latest list of certifications at: http://www.hp.com/go/isv

HP ZCENTRAL REMOTE BOOST SOFTWARE

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: http://www.hp.com/go/performanceadvisor

Software

Bing search for IE11



¹Only available in the US, and optional

Features

Buv Office

HP Hotkey Support

HP Noise Cancellation Software

HP Performance Advisor8

HP Z Central Remote Boost Software²

Native Miracast support 4

HP Connection Optimizer9

HP Smart Support²⁰

Security Management

Absolute persistence module 6

HP Device Access Manager

HP FingerPrint Sensor

HP Manageability Integration Kit11

HP Power On Authentication

HP Support Assistant

Security lock slot¹²

Trusted Platform Module TPM 2.0 Embedded Security Chip

Master Boot Record security

Pre-boot authentication

Microsoft Security Defender¹⁰

HP Client Security Manager¹⁷

HP BIOSphere Gen6 5

HP Sure Recover Gen3 13

HP Sure Start Gen6 5, 15

HP Secure Erase 16

HP Sure Sense¹⁸

HP Smart Support²⁰

BIOS Version

ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant

UEFI version: 2.7

TPM

Model: Infineon SLB9670 Version: 7.63.3353.0 Revision: TPM 2.0

FIPS 140-2 Compliant: Yes with Convert TPM to 2.0 (FIPS 140-2) option

Fingerprint Sensor (Optional)

Voltage: 3.0-3.6V

Operating temperature: -20° - 85°C

Imaging current: 31mA Wake on finger current: 40 uA Capture rate: 30ms/frame

ESD Resistance: IEC 6100-4-2 4B (+/-15KV)
Detection Matrix: 363 dpi, sensing area 8x8 mm

Security Features

HP Fingerprint Sensor (optional)¹⁹ IR Camera with Windows Hello

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

² HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7



Features

or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.

⁴ Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast.

⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.

⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

⁸ HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html ⁹ HP Connection Optimizer requires Windows 10.

¹⁰ Microsoft Defender Opt in and internet connection required for updates.

11 HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

¹² Nano Security lock slot is Lock sold separately.

¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel[®] Optane™.

¹⁵ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability. Some Sure Start features are limited to Windows Operating System. HP Sure Start end user notifications and HP Sure Start event logging support is limited to Windows Operating system. These features are not supported in Linux.

¹⁶ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

¹⁷ HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.

¹⁸ HP Sure Sense requires Windows 10 Pro or Enterprise. See product specifications for availability.

¹⁹ HP Fingerprint Sensor is optional.

²⁰ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



Features

POWER

Power Supply

Up to 18 hours1

HP Long Life 6-cell, 83 Wh Li-ion polymer²
Supports battery HP Fast Charge: approximately 50% in 30 minutes

HP Smart 150 W External AC Power Adapter³ HP Slim Smart 200 W External AC Power Adapter

ENVIRONMENTAL

ENERGY STAR® certified and EPEAT® GOLD registered configurations available¹ Low halogen²



¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details.

² Supports HP Fast Charge Technology (50% of the charge in 30 minutes)

³ Not available with NVIDIA Quadro RTX graphics configurations

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

35.4 x 23.46 x 1.79 cm - non-touch 35.4 x 23.46 x 1.75 cm - touch

13.93 x 9.24 x 0.70 in - non touch 13.93 x 9.24 x 0.69 in - touch

Max. hinge open angle on: 150°

Weights

Starting at 3.84 lbs (1.74kg)

Weight varies by configuration and components.

A deck: Anodized Aluminium with plastic bumper

B deck: Anodized Aluminium for Non-Touch sku; Touch has Corning® Gorilla® Glass 5

C deck: Anodized Aluminium D deck: Magnesium Die Cast

Metal Alloy Hinges

PORTS/SLOTS

Right side (configurations without NVIDIA Quadro RTX Graphics)

1 4.5mm AC power connector

2 Thunderbolt[™] 3 (40Gbps signaling rate) with SuperSpeed USB Type-C[®] 10Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.2, HP Sleep and Charge) [USB Type-C[®] with Thunderbolt[™] 3] 1 HDMI 2.0

1 SD 4.0 Media Reader^{1, 2}

Right side (configurations with NVIDIA Quadro RTX Graphics)

1 4.5mm AC power connector

2 Thunderbolt[™] 3 (40Gbps signaling rate) with SuperSpeed USB Type-C[®] 10Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.2, HP Sleep and Charge) [USB Type-C[®] with Thunderbolt[™] 3] 1 mini DisplayPort[™] 1.4 connector

1 SD 4.0 Media Reader^{1, 2}

Left side

1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging] 1 headphone/microphone combo

¹ SD Media does not come with the device and requires compatible media in order to use the slot.

²SD 4.0 supports next generation secure digital and is compatible to SD, SDHC, SDXC media

SERVICE AND SUPPORT

3-year limited warranty options available, depending on country. Batteries have a default one-year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. Optional 1 HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected



Features

by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power) Voltage

Nominal Operating

19.5 V

Average Operating

Power(MM14)

4.38W

Average Operating

Power(idle)

(Idle)

495mW (MSC) . 2.693W System in idle mode + max Adapter Safety test

panel brightness

condition

FHD panel: 400nits UHD panel: 600nits

Integrated graphics

45W<CPU (Intel did not define TDP for iGPU)

Discrete Graphics 35W

Max Operating Power

Discrete < 105W

UMA < 45W

Temperature

32° to 95° F (0° to 35° C) (Not Writing Optical) **Operating**

Non-operating -4° to 140° F (-20° to 60° C) (writing optical)

Relative Humidity

Operating

10% to 90%, non-condensing

Shock

Non-operating

5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Operating

40 G, 2 ms, half-sine

Non-operating

200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms

Maximum Altitude

Non-operating 1.50 grms

(unpressurized) **Planned Industry Standard**

Certifications

Operating -50 to 10,000 ft (-15.24 to 3,048 m) **Non-operating** -50 to 40,000 ft (-15.24 to 12,192 m)

UL Yes **CSA** Yes **FCC Compliance** Yes **ENERGY STAR®** Yes

EPEAT® Gold in United States² **EPEAT®** Yes

ICES Australia / NZ A-Tick

Compliance

Yes

CCC Yes Japan VCCI Compliance Yes KCC Yes **BSMI** Yes **CE Marking Compliance** Yes

MIL STD 810H Yes, Passed 21 Tests

BNCI or BELUS Yes CIT Yes Saudi Arabian

Compliance (ICCP) Yes Yes

²EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.



¹Configurations of the HP ZBook Studio G7 that are ENERGY STAR® qualified are identified as HP ZBook Studio G7 ENERGY STAR on HP websites and on http://www.energystar.gov.

Technical Specifications – Displays

DISPLAYS

15.6" diagonal, 4K UHD (3840 x 2160), IPS, antiglare, 600 nits, 100% DCI-P3, Next Gen HP DreamColor

 Outline Dimensions (W x H)
 350.22 x 216.37(mm) max

 Active Area
 344.22 x 193.62 (mm)

Weight 300g max.

Diagonal Size 15.6 inch

Thickness 2.6 (mm) max

Interface eDP1.4

Surface Treatment Anti-Glare

Contrast Ratio 1700:1 (typical)

Refresh Rate 60 Hz

Touch enabled

Brightness 600 nit typical (Panel Only)

No

Pixel Resolution Pitch 3840 x 2160 (UHD)

Backlight RGB PPI LED

Color Gamut Coverage DCI-P3 100%

Delta E <2

Color Depth 8 bits + 2 FRC
Viewing Angle UWVA 85/85/85/85

15.6" diagonal, FHD (1920 x 1080), IPS, antiglare, 400 nits, low power, 72% NTSClow power (1W) panel

 Outline Dimensions (W x H)
 349.46 x 215.9 max.

 Active Area
 344.16 x 193.59 typ.

Weight 310g max
Diagonal Size 15.6
Thickness 2.6t max.
Interface eDP 1.4
Surface Treatment Anti-glare (AG)

Touch enabled No

Contrast Ratio 1200:1 (typ)
Refresh Rate 60Hz
Brightness 400nit typ.

Pixel Resolution Pitch 1920 x 1080 (FHD)

Backlight RGB PPI LED

Color Gamut Coverage sRGB 100%

Color Depth 8bit

Viewing Angle UWVA 85/85/85

Technical Specifications – Displays

15.6" diagonal, 4K UHD Outline Dimer (3840 x 2160), touch, OLED UWVA, BrightView, Corning® Gorilla® Glass 6, Weight 400 nits, HDR 500, 100% Diagonal Size DCI-P3

Outline Dimensions (W x H) 348.348×216.202 (mm) max **Active Area** 344.2176 x 193.6224 (mm)

Weight 200g max.

Diagonal Size 15.6 (inch)

Thickness 2.195(mm) max

InterfaceeDP 1.4Surface TreatmentGlare (BV)

Touch enabledYesContrast Ratio100,000:1Refresh Rate60Hz

Brightness 400nit (Panel Only)

Pixel Resolution Pitch 3840 x 2160 (UHD)

BacklightRGBPPIOLED

Color Gamut Coverage DCI P3 100%
Color Depth 8 bits + 2 FRC
Viewing Angle UWVA 85/85/85/85

15.6" diagonal, FHD (1920 x 1080), IPS, antiglare, 1000 nits, 72% NTSC, HP Sure View Reflect integrated privacy screen

 Outline Dimensions (W x H)
 349.52 x 205.39 max.

 Active Area
 344.16 x 193.59 typ.

Weight 370g max.

Diagonal Size 15.6"

Thickness 2.6mm / 4.5mm max. (PCB)

Interface eDP
Surface Treatment LCD

Touch enabled Anti-glare (AG)

Contrast RatioNoRefresh Rate1500:1Brightness60Hz

Pixel Resolution Pitch 1920 x 1080 (FHD)

Backlight LED PPI 141

Color Gamut Coverage 100% sRGB **Color Depth** 8 bits

Viewing Angle UWVA 85/85/85



Technical Specifications – Storage

STORAGE AND DRIVES

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCle® Gen3 x4 NVMe™

Form Factor M.2 2280

Performance Maximum Sequential Read Maximum Sequential Write

2580 MB/s~ 2600 MB/s 1000 MB/s~ 1100 MB/s

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD) Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

 Interface
 PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2800 MB/s~ 2900 MB/s 1000 MB/s~ 1800 MB/s

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1 TB PCle® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD) Form Factor M.2 2280
Capacity 1TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

 Interface
 PCle® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

2900 MB/s ~ 3000 MB/s Up to 2000 MB/s

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security,TRIM; L1.2



2

2

Technical Specifications – Storage

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2 TB PCle® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD

2

Form Factor M.2 2280
Capacity 2 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (<10 g)</td>

Interface PCIe® Gen3 x4 NVMe™

Performance Maximum Sequential Read Maximum Sequential Write

Up to 2900MB/s Up to 2100 MB/s

Logical Blocks 3,907,029,168

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Technical Specifications - Networking

NETWORKING/COMMUNICATION

| NET WORKING/COMMONICATION | | |
|---|--------------------------------|--|
| Intel® Wi-Fi 64 AX201 and Bluetooth® 5.0 802.11ax (2 x 2) (Supporting gigabit file transfer speeds) vPro®1* | Wireless LAN Standards | IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11t IEEE 802.11r IEEE 802.11r |
| | Interoperability | Wi-Fi certified |
| | Frequency Band | 802.11b/g/n/ax • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz |
| | Data Rates | 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) |
| | Modulation | Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM |
| | Security ¹ | IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI |
| | Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) |
| | | • |
| | Roaming | IEEE 802.11 compliant roaming between access points |



802.11b: +18.5dBm minimum
802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
 802.11n HT40(2.4GHz): +14.5dBm minimum
 802.11n HT20(5GHz): +15.5dBm minimum
 802.11n HT40(5GHz): +14.5dBm minimum

Output Power²

Technical Specifications – Networking

802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

• Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum
• 802.11a/g, 6Mbps: -86dBm maximum
• 802.11a/g, 54Mbps: -72dBm maximum
• 802.11n, MCS07: -67dBm maximum
• 802.11n, MCS15: -64dBm maximum
• 802.11ac, MCS0: -84dBm maximum
• 802.11ac, MCS9: -59dBm maximum
• 802.11ax, MCS11(HT40): -59dBm maximum

•802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230 : 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber — Radio Off; LED Off — Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)



Technical Specifications – Networking

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro® support with appropriate Intel® chipset components

Intel® Wi-Fi 61 AX201 and Bluetooth 5.0 (802.11ax 2 x 2, nonvPro®, supporting gigabit file transfer speeds) nonvPro® Wireless LAN Standards IEEE 802.11a

IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11b

IEEE 802.11i IEEE 802.11k IEEE 802.11r

IEEE 802.11v

InteroperabilityWi-Fi certifiedFrequency Band802.11b/g/n/ax

2.402 – 2.482 GHz
 802.11a/n/ac/ax
 4.9 – 4.95 GHz (Japan)
 5.15 – 5.25 GHz



Technical Specifications – Networking

5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

60MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz

& 160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

Security¹ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g

mode only

• AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

• 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum

• 802.11n HT20(5GHz) : +15.5dBm minimum

802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum

• 802.11ac VHT160(5GHz): +11.5dBm minimum

• 802.11ax HT40(2.4GHz): +10dBm minimum

• 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode :2.0 W

• Receive mode: 1.6 W

• Idle mode (PSP) 180 mW (WLAN Associated)

• Idle mode :50 mW (WLAN unassociated)

Connected Standby/Modern Standby: 10mW

· Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum

802.11a/g, 6Mbps: -86dBm maximum

• 802.11a/g, 54Mbps : -72dBm maximum

• 802.11n, MCS07 : -67dBm maximum

• 802.11n, MCS15 : -64dBm maximum

• 802.11ac, MCS0: -84dBm maximum

• 802.11ac, MCS9 : -59dBm maximum

Technical Specifications – Networking

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230 : 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

HumidityOperating 10% to 90% (non-condensing)
Non-operating 5% to 95% (non-condensing)

Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber - Radio OFF; LED White - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Altitude

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer



Technical Specifications – Networking

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 -Link Layer Privacy
LE Privacy 1.2 -Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)



Technical Specifications – Power

POWER

150 Watt Smart Slim AC Adapter
 Dimensions
 138x66x22mm

 Weight
 unit: 325g +/- 10g

Input Efficiency 88% at 115 Vac and 89% at 230 Vac

Input frequency 47 ~ 63 Hz

range

Input AC current 2.7 A at 90 Vac and Maximum Load

Output Output power 150W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <16.0A

Connector 4.5mm Barrel Type

Environmental DesignOperating temperature
32° to 95° F (0° to 35° C)

Non-operating

(storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

47 to 63 Hz

2.9 A at 90 Vac and Maximum Load

200 Watt Smart Slim AC Adapter

 Dimensions
 152x73x23.5mm

 Weight
 unit: 530g +/- 10g

Input Input Efficiency 88% at 115 Vac and 89% at 230Vac

Input frequency

Input AC current

range

re

Output Output power 200W

DC output 19.5V

Hold-up time 5ms at 115 Vac input

Output current limit <16.0A

Connector 4.5mm Barrel Type

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Technical Specifications - Power

Non-operating -4° to 185° F (-20° to 85° C)

(storage) temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.



Technical Specifications – Power

HP 6-cell Long Life Li-lon Dimensions (H x W x L) 7.78x71.05x316.1 mm (0.306 x 2.797 x 12.44 inch)

(83 WHr) Weight 0.305kg(0.67lb)

Cells/Type3cell Lithium-Ion Polymer cellEnergyVoltage11.58V

Amp-hour capacity 7.17Ah / 6.88Ah

Watt-hour capacity 83Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 122° F (-10° to 60° C)

Fuel Gauge LED NA
Warranty 1-year⁶
Optional Travel Battery No

Available

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test method)

| 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
|--------------|----------------------------|--|
| 9.62 W | 10.54 W | 9.37 W |
| 0.95 W | 1.07 W | 0.98 W |
| 0.95 W | 1.07 W | 0.98 W |
| 0.36 W | 0.47 W | 0.34 W |
| | 9.62 W 0.95 W 0.95 W | 9.62 W 10.54 W 0.95 W 1.07 W 0.95 W 1.07 W |

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
|-------------------------------|----------------|----------------|----------------|
| Normal Operation (Short idle) | 32.9004 BTU/hr | 36.0468 BTU/hr | 32.0454 BTU/hr |
| Normal Operation (Long idle) | 3.249 BTU/hr | 3.6594 BTU/hr | 3.3516 BTU/hr |
| Sleep | 3.249 BTU/hr | 3.6594 BTU/hr | 3.3516 BTU/hr |
| Off | 1 2312 RTII/hr | 1 6074 RTH/hr | 1 1628 RTII/hr |

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Typically Configured – Idle Fixed Disk – Random writes

Longevity and Upgrading

| Sound Power (L _{WAd} , bels) | Sound Pressure $(L_{pAm}, decibels)$ |
|--|--------------------------------------|
| 2.5 | 22 |
| 3.6 | 35.5 |

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

• 1 M.2 2280 PCIe Gen 3 x 4 NVMe Solid State Drive Slot (does not support SATA M.2 2280 drives)

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC



Technical Specifications – Environmental

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 7.8% post-consumer recycled plastic (by wt.)
- This product is 96.1% recycle-able when properly disposed of at end of life.

| Packaging Mat |
|----------------------|
|----------------------|

| External: | PAPER/Corrugated | 1292 g |
|-----------|---|--------|
| | PAPER/Paper | 20 g |
| | PAPER/Molded pulp | 307 g |
| Internal: | PLASTIC/Polyethylene low density - LDPE | 10 g |
| | PLASTIC/Polyester | 10 g |
| | PLASTIC/Polypropylene - PP | 7 g |

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):

- Ashestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehvde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)



Technical Specifications - Environmental

- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



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| Date of change: | Version History: | | Description of change: |
|--------------------|------------------|---------|---|
| September 28, 2020 | From v1 to v2 | Changed | WEIGHTS & DIMENSIONS section |
| October 1, 2020 | From v2 to v3 | Changed | At A Glance, STORAGE AND DRIVES and SOFTWARE AND SECURITY sections |
| November 18, 2020 | From v3 to v4 | Changed | At A Glance, OPERATING SYSTEM, GRAPHICS, STORAGE AND DRIVES, PORTS/SLOTS sections |
| December 16, 2020 | From v4 to v5 | Added | BIOS Version in Software and Security section |
| April 22, 2021 | From v5 to v6 | Changed | INTEL CORE IS WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE and NETWORKING/COMMUNICATIONS sections |
| May 11, 2021 | From v6 to v7 | Changed | WEIGHTS & DIMENSIONS section |
| May 20, 2021 | From v7 to v8 | Changed | Graphics and SOFTWARE AND SECURITY sections |
| May 31, 2021 | From v8 to v9 | Added | HP Smart Support and footnote |
| June 16, 2021 | From v9 to v10 | Changed | SYSTEM UNIT Temperature section |
| July 22, 2021 | From v10 to v11 | Removed | HDR400 and True Black references |
| August 11, 2021 | From v11 to v12 | Changed | WEIGHTS & DIMENSIONS section |

